

积层贴片陶瓷片式电容器

C2012X5R1C335M085AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X5R1C335MT****
用途	一般等级 车载用途时为 CGA4J3X5R1C335M125AB 。
特点	General 一般 (~75V)
系列	C2012 [EIA 0805]
状态	量产体制(新设计非推荐)



尺寸

长度(L)	2.00mm ±0.20mm
宽度(W)	1.25mm ±0.20mm
厚度(T)	0.85mm ±0.15mm
端子宽度(B)	0.20mm Min.
端子间隔(G)	0.50mm Min.
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

电气特性

电容	3.3 μF ±20%
额定电压	16VDC
温度特性	X5R(±15%)
耗散因数 (Max.)	7.5%
绝缘电阻 (Min.)	30MΩ

其他

焊接方法	流体 回流
AEC-Q200	NO
包装形式	纸编带 (180mm卷筒)
包装个数	4000pcs

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

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特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images

